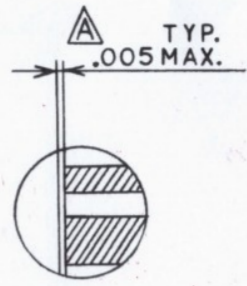
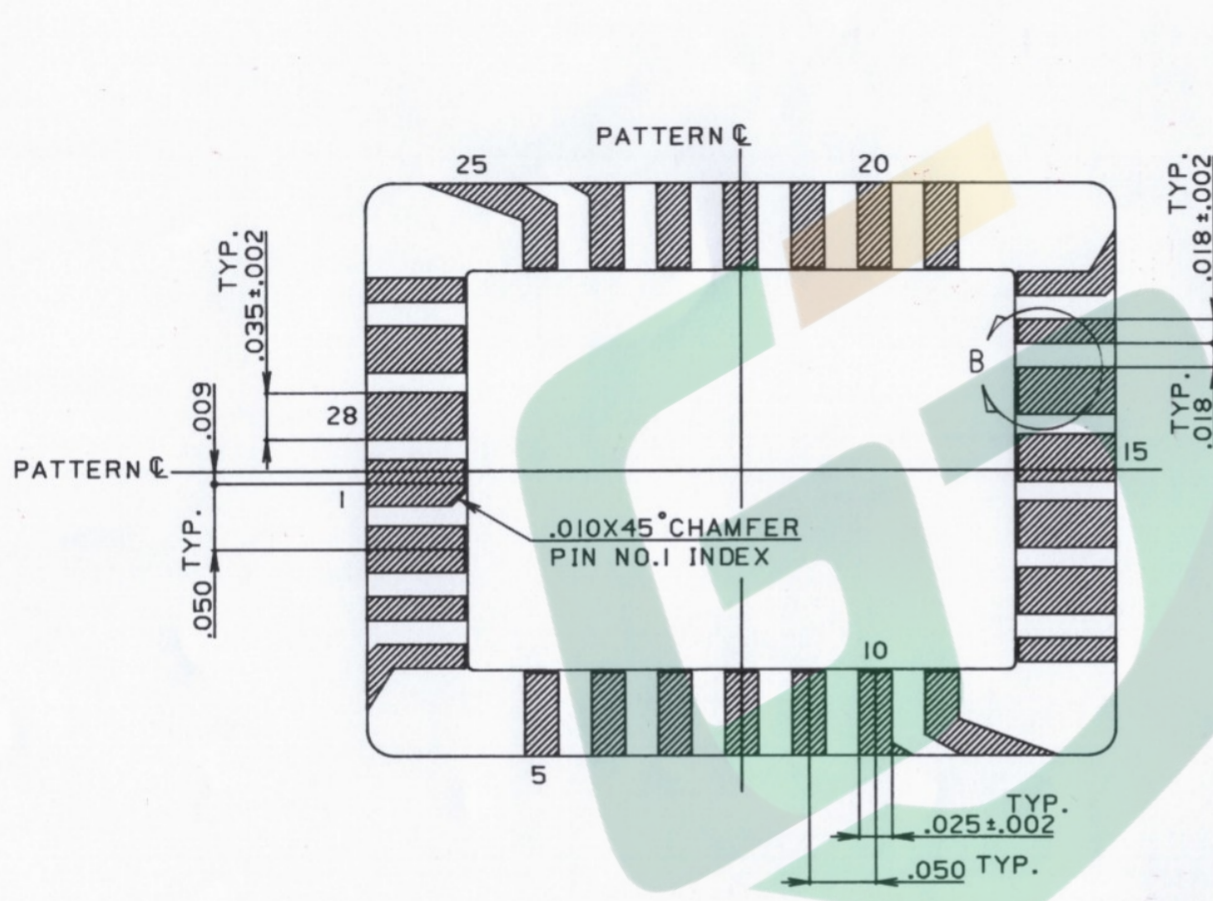


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DETAIL-B

- NOTES.
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE : 0.15Ω MAX. AT PIN NO.1, 2,13,14,15,16,27,28. OTHER LESS THAN 1.0Ω MAX.

BONDING PATTERN



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